

ABSTRACT OF THE DISCLOSURE

The present invention provides an inspection apparatus for an electrode plate-connected structure for a secondary cell for inspecting each bonding portion of an electrode plate-connected structure for a secondary cell including a plurality of electrode plates which are arranged in parallel to one another at prescribed intervals and are perpendicularly connected to a power collecting plate. The apparatus is characterized by including: a lighting section for irradiating light to each of the bonded portions of the plurality of electrode plates and the power collecting plate; a light receiving section for detecting a projected image of each of the bonded portions based on the light irradiated to the electrode plate-connected structure by the lighting section; and an evaluation section for evaluating a bonding state of each of the bonding portions based on the projected image of each of the bonded portions detected by the light receiving section.

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